

LM2907/LM2917 Frequency to Voltage Converter

Check for Samples: LM2907-N, LM2917-N

FEATURES

- **Ground Referenced Tachometer Input Interfaces Directly With Variable Reluctance Magnetic Pickups**
- **Op Amp/Comparator Has Floating Transistor** Output
- 50 mA Sink or Source to Operate Relays, Solenoids, Meters, or LEDs
- **Frequency Doubling For Low Ripple**
- **Tachometer Has Built-In Hysteresis With** Either Differential Input or Ground Referenced
- **Built-In Zener on LM2917**
- ±0.3% Linearity Typical
- **Ground Referenced Tachometer is Fully Protected From Damage Due to Swings Above** V_{CC} and Below Ground

APPLICATIONS

- **Over/Under Speed Sensing**
- **Frequency to Voltage Conversion** (Tachometer)
- **Speedometers**
- **Breaker Point Dwell Meters**
- **Hand-Held Tachometer**
- **Speed Governors**
- **Cruise Control**
- **Automotive Door Lock Control**
- Clutch Control
- **Horn Control**
- **Touch or Sound Switches**

ADVANTAGES

- **Output Swings to Ground For Zero Frequency**
- Easy to Use; $V_{OUT} = f_{IN} \times V_{CC} \times R1 \times C1$
- Only One RC Network provides Frequency **Doubling**
- Zener Regulator on Chip allows Accurate and Stable Frequency to Voltage or Current Conversion (LM2917)

DESCRIPTION

The LM2907, LM2917 series are monolithic frequency to voltage converters with a high gain op amp/comparator designed to operate a relay, lamp, or other load when the input frequency reaches or exceeds a selected rate. The tachometer uses a charge pump technique and offers frequency doubling for low ripple, full input protection in two versions (LM2907-8, LM2917-8) and its output swings to ground for a zero frequency input.

The op amp/comparator is fully compatible with the tachometer and has a floating transistor as its output. This feature allows either a ground or supply referred load of up to 50 mA. The collector may be taken above V_{CC} up to a maximum V_{CE} of 28V.

The two basic configurations offered include an 8-pin device with a ground referenced tachometer input and an internal connection between the tachometer output and the op amp non-inverting input. This version is well suited for single speed or frequency switching or fully buffered frequency to voltage conversion applications.

The more versatile configurations provide differential tachometer input and uncommitted op amp inputs. With this version the tachometer input may be floated and the op amp becomes suitable for active filter conditioning of the tachometer output.

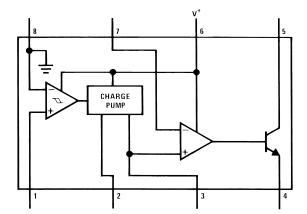
Both of these configurations are available with an active shunt regulator connected across the power leads. The regulator clamps the supply such that stable frequency to voltage and frequency to current operations are possible with any supply voltage and a suitable resistor.

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CONNECTION DIAGRAMS

PDIP and SOIC Packages, Top Views



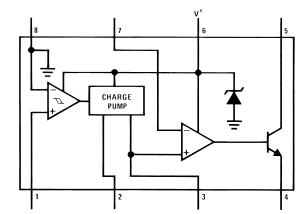


Figure 1. See Package Number D0008A or P0008E

Figure 2. See Package Number D0008A or P0008E

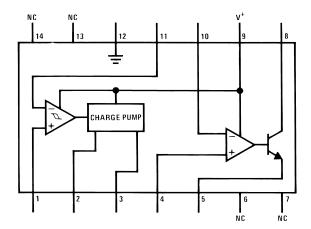


Figure 3. See Package Number D0014A or NFF0014A

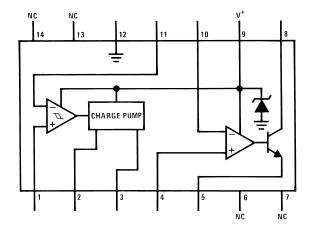


Figure 4. See Package Number D0014A or NFF0014A





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS(1)(2)

| Supply Voltage | | | 28V | | | | |
|-------------------------------|---------------------------------------|--------------------------|-----------------|--|--|--|--|
| Supply Current (Zener Options | s) | | 25 mA | | | | |
| Collector Voltage | | | 28V | | | | |
| Differential Input Voltage | Differential Input Voltage Tachometer | | | | | | |
| | Op Amp/Comparator | Op Amp/Comparator | | | | | |
| Input Voltage Range | Tachometer | LM2907-8, LM2917-8 | ±28V | | | | |
| | | LM2907, LM2917 | 0.0V to +28V | | | | |
| | Op Amp/Comparator | Op Amp/Comparator | | | | | |
| Power Dissipation | LM2907-8, LM2917-8 | LM2907-8, LM2917-8 | | | | | |
| | LM2907-14, LM2917-14 ⁽¹⁾ | LM2917-14 ⁽¹⁾ | | | | | |
| Operating Temperature Range | • | | -40°C to +85°C | | | | |
| Storage Temperature Range | | | -65°C to +150°C | | | | |
| Soldering Information | PDIP Package | Soldering (10 seconds) | 260°C | | | | |
| | SOIC Package | Vapor Phase (60 seconds) | 215°C | | | | |
| | | Infrared (15 seconds) | 220°C | | | | |

For operation in ambient temperatures above 25°C, the device must be derated based on a 150°C maximum junction temperature and a thermal resistance of 101°C/W junction to ambient for LM2907-8 and LM2917-8, and 79°C/W junction to ambient for LM2907-14 and

ELECTRICAL CHARACTERISTICS

 $V_{CC} = 12 V_{DC}$, $T_A = 25$ °C, see test circuit

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|---------------------------------|------------------------------|---|------|-----|-----------------------|-------|
| TACHOMETER | | | , | | | |
| | Input Thresholds | V _{IN} = 250 mVp-p @ 1 kHz ⁽¹⁾ | ±10 | ±25 | ±40 | mV |
| | Hysteresis | V _{IN} = 250 mVp-p @ 1 kHz ⁽¹⁾ | | 30 | | mV |
| | Offset Voltage | V _{IN} = 250 mVp-p @ 1 kHz ⁽¹⁾ | | | | |
| | LM2907/LM2917 | | | 3.5 | 10 | mV |
| | LM2907-8/LM2917-8 | | | 5 | 15 | mV |
| | Input Bias Current | $V_{IN} = \pm 50 \text{ mV}_{DC}$ | | 0.1 | 1 | μΑ |
| V _{OH} | Pin 2 | $V_{IN} = +125 \text{ mV}_{DC}^{(2)}$ | | 8.3 | | V |
| V _{OL} | Pin 2 | $V_{IN} = -125 \text{ mV}_{DC}^{(2)}$ | | 2.3 | | V |
| l ₂ , l ₃ | Output Current | $V2 = V3 = 6.0V^{(3)}$ | 140 | 180 | 240 | μΑ |
| l ₃ | Leakage Current | I2 = 0, V3 = 0 | | | 0.1 | μΑ |
| K | Gain Constant | See ⁽²⁾ | 0.9 | 1.0 | 1.1 | |
| | Linearity | f _{IN} = 1 kHz, 5 kHz, 10 kHz ⁽⁴⁾ | -1.0 | 0.3 | +1.0 | % |
| OP/AMP COMP | ARATOR | | | | , | |
| V _{OS} | | V _{IN} = 6.0V | | 3 | 10 | mV |
| I _{BIAS} | | V _{IN} = 6.0V | | 50 | 500 | nA |
| | Input Common-Mode Voltage | | 0 | | V _{CC} -1.5V | V |

Product Folder Links: LM2907-N LM2917-N

If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

Hysteresis is the sum +V_{TH} - (-V_{TH}), offset voltage is their difference. See test circuit. V_{OH} is equal to $^{3}\!\!/ \times V_{CC}$ - 1 V_{BE} , V_{OL} is equal to $^{3}\!\!/ \times V_{CC}$ - 1 V_{BE} , V_{OL} is equal to $^{3}\!\!/ \times V_{CC}$ - 1 V_{BE} , V_{OL} is equal to $^{3}\!\!/ \times V_{CC}$ - 1 V_{BE} , V_{OL} is equal to $^{3}\!\!/ \times V_{CC}$ - 1 V_{BE} , and the mirror gain, V_{CC} - 1 V_{CC}

Be sure when choosing the time constant R1 x C1 that R1 is such that the maximum anticipated output voltage at pin 3 can be reached with $I_3 \times R1$. The maximum value for R1 is limited by the output resistance of pin 3 which is greater than 10 $M\Omega$ typically.

Nonlinearity is defined as the deviation of V_{OUT} (@ pin 3) for f_{IN} = 5 kHz from a straight line defined by the V_{OUT} @ 1 kHz and V_{OUT} @ 10 kHz. C1 = 1000 pF, R1 = 68k and C2 = 0.22 mFd.



ELECTRICAL CHARACTERISTICS (continued)

 $V_{CC} = 12 V_{DC}$, $T_A = 25$ °C, see test circuit

| Parameter | Conditions | Min | Тур | Max | Units |
|-----------------------|--|---|--|--|--|
| Voltage Gain | | | 200 | | V/mV |
| Output Sink Current | V _C = 1.0 | 40 | 50 | | mA |
| Output Source Current | V _E = V _{CC} -2.0 | | 10 | | mA |
| Saturation Voltage | I _{SINK} = 5 mA | | 0.1 | 0.5 | V |
| | I _{SINK} = 20 mA | | | 1.0 | V |
| | I _{SINK} = 50 mA | | 1.0 | 1.5 | V |
| TOR | | | | | • |
| Regulator Voltage | $R_{DROP} = 470\Omega$ | | 7.56 | | V |
| Series Resistance | | | 10.5 | 15 | Ω |
| Temperature Stability | | | +1 | | mV/°C |
| Total Supply Current | | | 3.8 | 6 | mA |
| | Voltage Gain Output Sink Current Output Source Current Saturation Voltage TOR Regulator Voltage Series Resistance Temperature Stability | $\begin{tabular}{lllllllllllllllllllllllllllllllllll$ | $\begin{tabular}{c cccc} Voltage Gain & & & & & & & & & & & & & & & & & & &$ | $\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$ | $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$ |

TEST CIRCUIT AND WAVEFORM

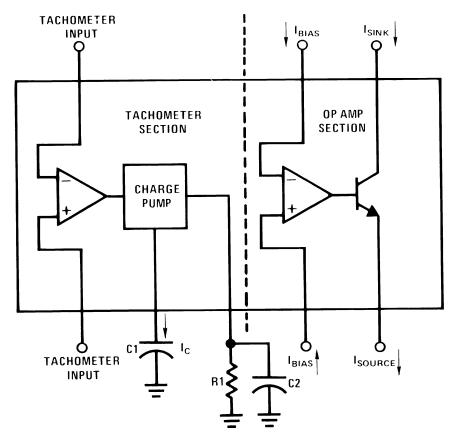


Figure 5.



Tachometer Input Threshold Measurement

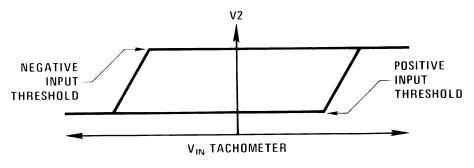
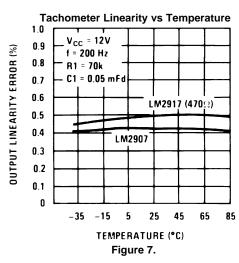
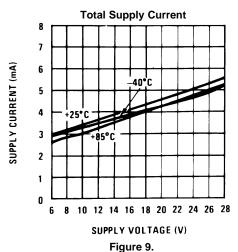


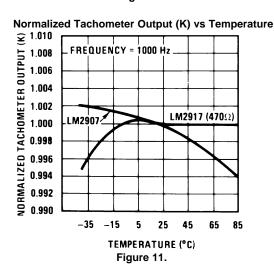
Figure 6.

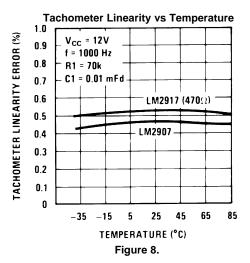


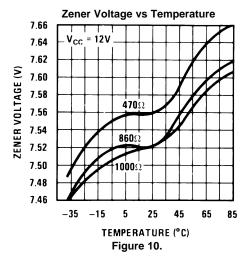
TYPICAL PERFORMANCE CHARACTERISTICS

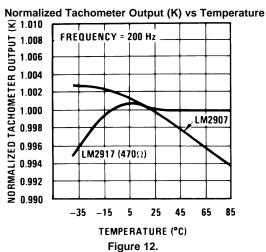






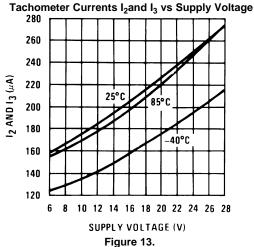


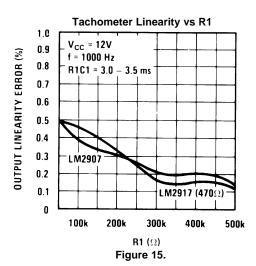


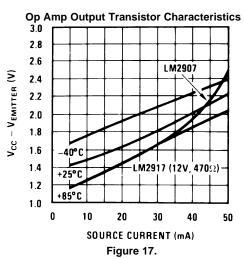


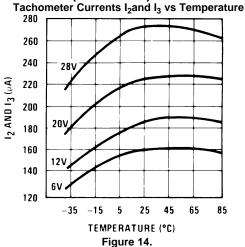


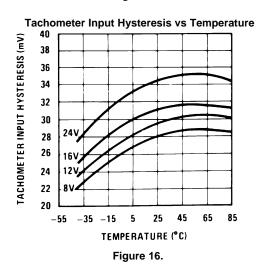
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

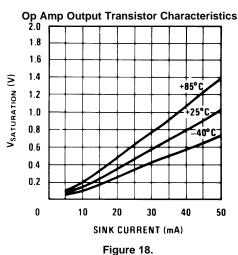














APPLICATIONS INFORMATION

The LM2907 series of tachometer circuits is designed for minimum external part count applications and maximum versatility. In order to fully exploit its features and advantages let's examine its theory of operation. The first stage of operation is a differential amplifier driving a positive feedback flip-flop circuit. The input threshold voltage is the amount of differential input voltage at which the output of this stage changes state. Two options (LM2907-8, LM2917-8) have one input internally grounded so that an input signal must swing above and below ground and exceed the input thresholds to produce an output. This is offered specifically for magnetic variable reluctance pickups which typically provide a single-ended ac output. This single input is also fully protected against voltage swings to ±28V, which are easily attained with these types of pickups.

The differential input options (LM2907, LM2917) give the user the option of setting his own input switching level and still have the hysteresis around that level for excellent noise rejection in any application. Of course in order to allow the inputs to attain common-mode voltages above ground, input protection is removed and neither input should be taken outside the limits of the supply voltage being used. It is very important that an input not go below ground without some resistance in its lead to limit the current that will then flow in the epi-substrate diode.

Following the input stage is the charge pump where the input frequency is converted to a dc voltage. To do this requires one timing capacitor, one output resistor, and an integrating or filter capacitor. When the input stage changes state (due to a suitable zero crossing or differential voltage on the input) the timing capacitor is either charged or discharged linearly between two voltages whose difference is $V_{CC}/2$. Then in one half cycle of the input frequency or a time equal to $1/2 f_{IN}$ the change in charge on the timing capacitor is equal to $V_{CC}/2 \times C1$. The average amount of current pumped into or out of the capacitor then is:

$$\frac{\Delta Q}{T} = i_{c(AVG)} = C1 \times \frac{V_{CC}}{2} \times (2f_{IN}) = V_{CC} \times f_{IN} \times C1$$
(1)

The output circuit mirrors this current very accurately into the load resistor R1, connected to ground, such that if the pulses of current are integrated with a filter capacitor, then $V_O = i_C \times R1$, and the total conversion equation becomes:

$$V_O = V_{CC} \times f_{IN} \times C1 \times R1 \times K$$

where

The size of C2 is dependent only on the amount of ripple voltage allowable and the required response time.

CHOOSING R1 AND C1

There are some limitations on the choice of R1 and C1 which should be considered for optimum performance. The timing capacitor also provides internal compensation for the charge pump and should be kept larger than 500 pF for very accurate operation. Smaller values can cause an error current on R1, especially at low temperatures. Several considerations must be met when choosing R1. The output current at pin 3 is internally fixed and therefore $V_{\rm O}/R1$ must be less than or equal to this value. If R1 is too large, it can become a significant fraction of the output impedance at pin 3 which degrades linearity. Also output ripple voltage must be considered and the size of C2 is affected by R1. An expression that describes the ripple content on pin 3 for a single R1C2 combination is:

$$V_{RIPPLE} = \frac{V_{CC}}{2} \times \frac{C1}{C2} \times \left(1 - \frac{V_{CC} \times f_{IN} \times C1}{I_2}\right) pk - pk$$
(3)

It appears R1 can be chosen independent of ripple, however response time, or the time it takes V_{OUT} to stabilize at a new voltage increases as the size of C2 increases, so a compromise between ripple, response time, and linearity must be chosen carefully.

As a final consideration, the maximum attainable input frequency is determined by V_{CC}, C1 and I₂:

$$f_{MAX} = \frac{I_2}{C1 \times V_{CC}} \tag{4}$$



USING ZENER REGULATED OPTIONS (LM2917)

For those applications where an output voltage or current must be obtained independent of supply voltage variations, the LM2917 is offered. The most important consideration in choosing a dropping resistor from the unregulated supply to the device is that the tachometer and op amp circuitry alone require about 3 mA at the voltage level provided by the zener. At low supply voltages there must be some current flowing in the resistor above the 3 mA circuit current to operate the regulator. As an example, if the raw supply varies from 9V to 16V, a resistance of 470Ω will minimize the zener voltage variation to 160 mV. If the resistance goes under 400Ω or over 600Ω the zener variation quickly rises above 200 mV for the same input variation.

TYPICAL APPLICATIONS

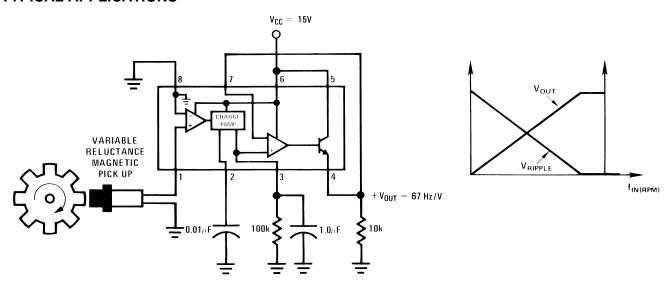


Figure 19. Minimum Component Tachometer

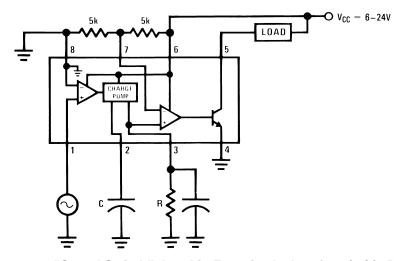


Figure 20. "Speed Switch", Load is Energized when $f_{IN} \ge (1 / (2RC))$



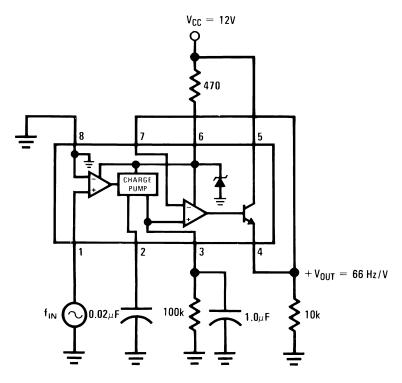


Figure 21. Zener Regulated Frequency to Voltage Converter

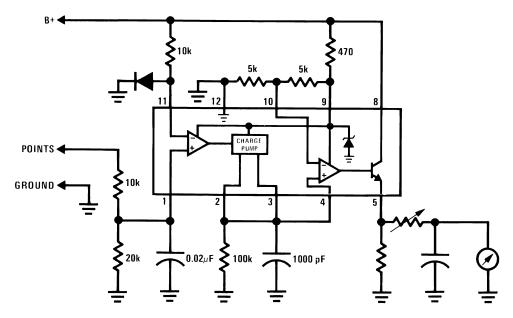


Figure 22. Breaker Point Dwell Meter



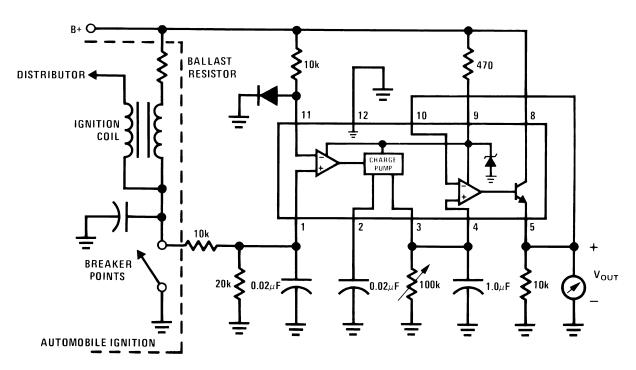


Figure 23. Voltage Driven Meter Indicating Engine RPM $V_0 = 6V @ 400 \text{ Hz}$ or 6000 ERPM (8 Cylinder Engine)

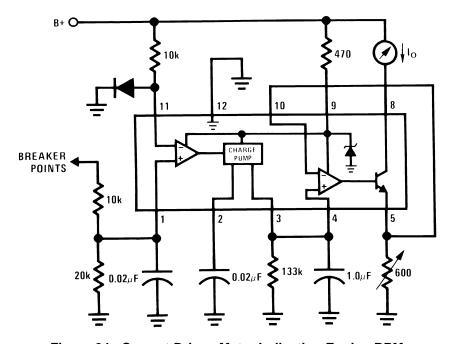


Figure 24. Current Driven Meter Indicating Engine RPM I_0 = 10 mA @ 300 Hz or 6000 ERPM (6 Cylinder Engine)



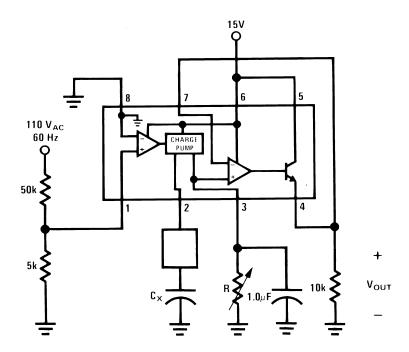


Figure 25. Capacitance Meter V_{OUT} = 1V–10V for CX = 0.01 to 0.1 mFd (R = 111k)

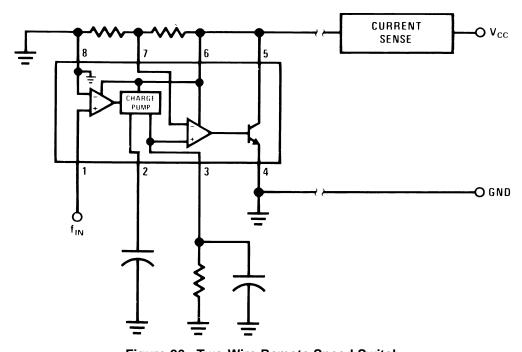
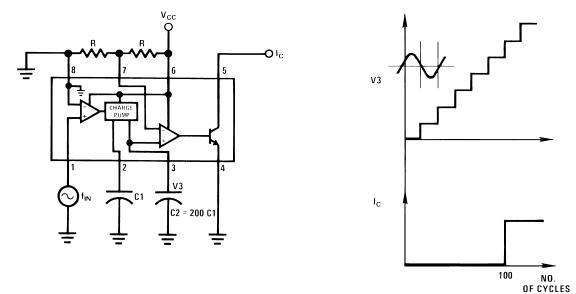


Figure 26. Two-Wire Remote Speed Switch



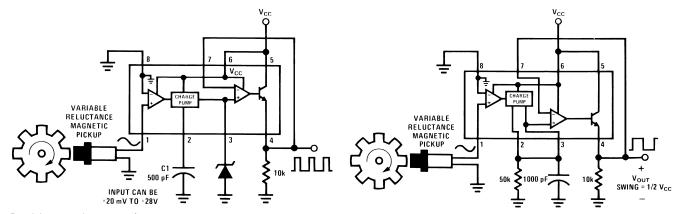


V3 steps up in voltage by the amount for each complete input cycle (2 zero crossings)

if C2 = 200 C1 after 100 consecutive input cycles. $V3 = 1/2 V_{CC}$

Figure 27. 100 Cycle Delay Switch

Variable Reluctance Magnetic Pickup Buffer Circuits



Precision two-shot output frequency equals twice input frequency. Pulse width = $\frac{V_{CC}}{2} \frac{C1}{12}$

Pulse width =
$$\frac{V_{CC}}{2} \frac{C1}{12}$$

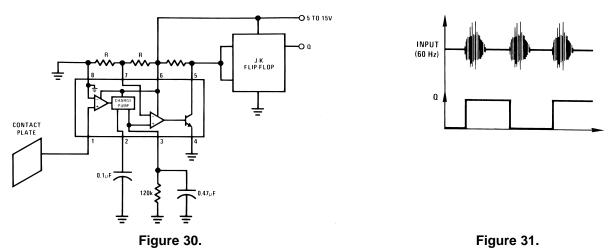
Pulse height = V_{ZENER}

Figure 28.

Figure 29.



Finger Touch or Contact Switch

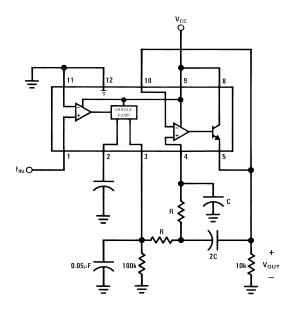


430
430
68
68
150
100k
1.0_{j.}F
100k
1.0_{j.}F
100k

Flashing begins when $f_{\text{IN}} \ge 100 \text{ Hz}$. Flash rate increases with input frequency increase beyond trip point.

Figure 32. Flashing LED Indicates Overspeed

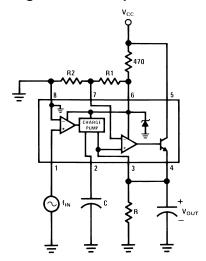




$$\begin{split} f_{POLE} &= \frac{0.707}{2\pi RC} \\ \tau_{RESPONSE} &= \frac{2.57}{2\pi f_{POLE}} \end{split}$$

Figure 33. Frequency to Voltage Converter with 2 Pole Butterworth Filter to Reduce Ripple

Figure 34. Overspeed Latch



Output latches when $f_{1N} = \frac{R2}{R1 + R2} \frac{1}{RC}$ Reset by removing V_{CC} .

Figure 35.

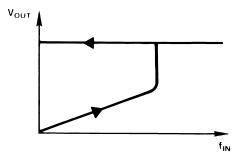
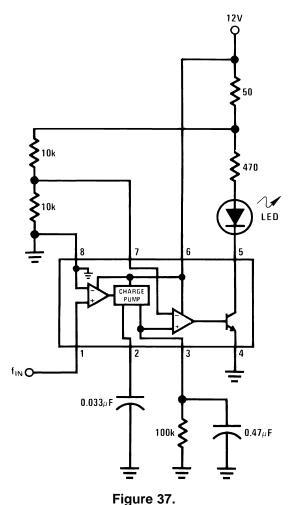


Figure 36.



Frequency Switch Applications

Some frequency switch applications may require hysteresis in the comparator function which can be implemented in several ways.



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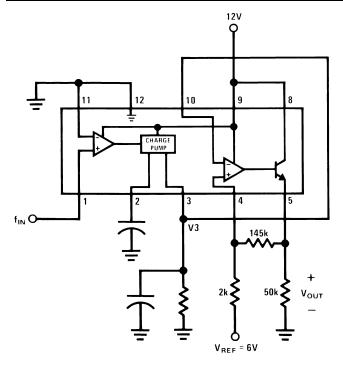


Figure 38.

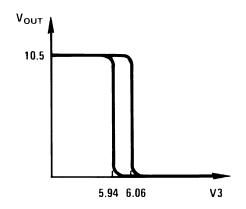


Figure 40.

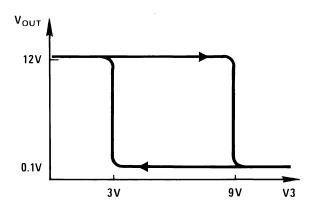
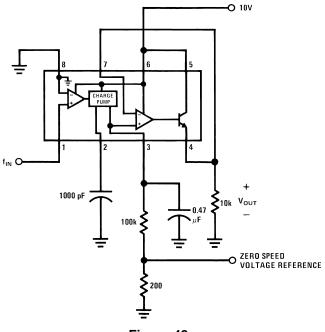


Figure 39.

Figure 41.



Changing the Output Voltage for an Input Frequency of Zero



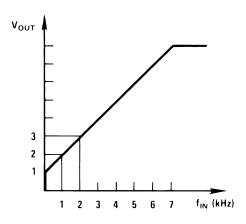
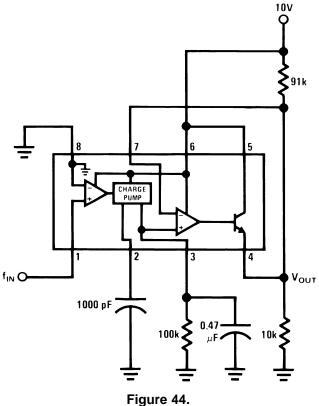


Figure 42.

Figure 43.

Changing Tachometer Gain Curve or Clamping the Minimum Output Voltage



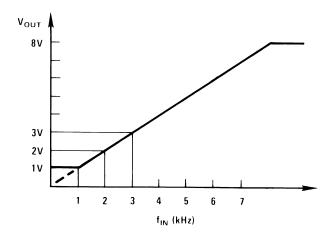
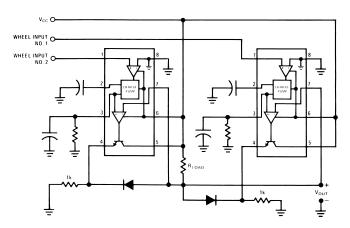


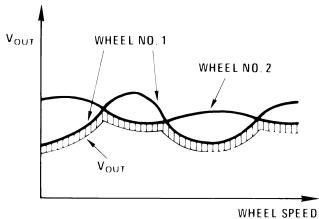
Figure 45.



ANTI-SKID CIRCUIT FUNCTIONS

"Select-Low" Circuit



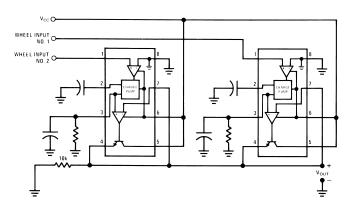


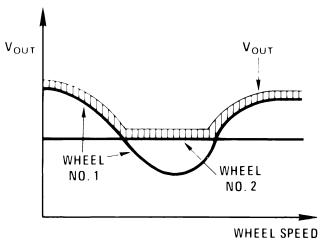
V_{OUT} Proportional to the Lower of the Two Input Wheel Speeds

Figure 46.

Figure 47.

"Select-High" Circuit





V_{OUT} Proportional to the Higher of the Two Input Wheel Speeds

Figure 48.

Figure 49.



"Select-Average" Circuit

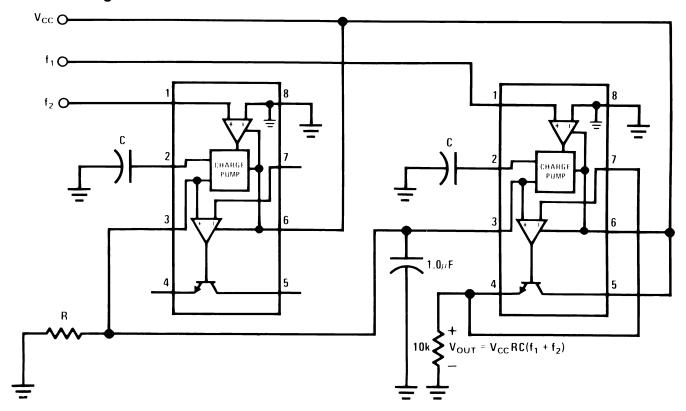
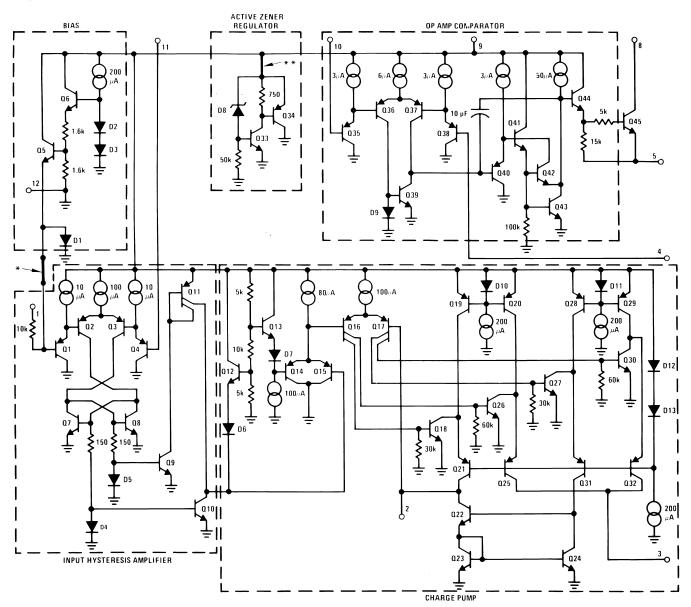


Figure 50.



EQUIVALENT SCHEMATIC DIAGRAM



^{*}This connection made on LM2907-8 and LM2917-8 only.

Figure 51.

^{**}This connection made on LM2917 and LM2917-8 only.

SNAS555C - JUNE 2000 - REVISED MARCH 2013



REVISION HISTORY

| Changes from Revision B (March 2013) to Revision C Changed layout of National Data Sheet to TI format | | Page |
|--|--|------|
| • | Changed layout of National Data Sheet to TI format | 21 |





7-Oct-2013

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|----------------------------|------------------|--------------------|--------------|----------------------|---------|
| LM2907M | ACTIVE | SOIC | D | 14 | 55 | TBD | Call TI | Call TI | -40 to 85 | LM2907M | Samples |
| LM2907M-8 | ACTIVE | SOIC | D | 8 | 95 | TBD | Call TI | Call TI | -40 to 85 | LM29 07M-8 | Samples |
| LM2907M-8/NOPB | ACTIVE | SOIC | D | 8 | 95 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM29 07M-8 | Samples |
| LM2907M/NOPB | ACTIVE | SOIC | D | 14 | 55 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM2907M | Samples |
| LM2907MX | ACTIVE | SOIC | D | 14 | 2500 | TBD | Call TI | Call TI | -40 to 85 | LM2907M | Samples |
| LM2907MX-8/NOPB | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM29 07M-8 | Samples |
| LM2907MX/NOPB | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM2907M | Samples |
| LM2907N | ACTIVE | PDIP | NFF | 14 | 25 | TBD | Call TI | Call TI | -40 to 85 | LM2907N | Samples |
| LM2907N-8 | ACTIVE | PDIP | Р | 8 | 40 | TBD | Call TI | Call TI | -40 to 85 | LM 2907N-8 | Samples |
| LM2907N-8/NOPB | ACTIVE | PDIP | Р | 8 | 40 | Green (RoHS & no Sb/Br) | CU SN | Level-1-NA-UNLIM | -40 to 85 | LM 2907N-8 | Samples |
| LM2907N/NOPB | ACTIVE | PDIP | NFF | 14 | 25 | Green (RoHS & no Sb/Br) | CU SN | Level-1-NA-UNLIM | -40 to 85 | LM2907N | Samples |
| LM2917M | ACTIVE | SOIC | D | 14 | 55 | TBD | Call TI | Call TI | -40 to 85 | LM2917M | Samples |
| LM2917M-8 | ACTIVE | SOIC | D | 8 | 95 | TBD | Call TI | Call TI | -40 to 85 | LM29 17M-8 | Samples |
| LM2917M-8/NOPB | ACTIVE | SOIC | D | 8 | 95 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM29 17M-8 | Samples |
| LM2917M/NOPB | ACTIVE | SOIC | D | 14 | 55 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM2917M | Samples |
| LM2917MX-8 | ACTIVE | SOIC | D | 8 | 2500 | TBD | Call TI | Call TI | -40 to 85 | LM29 17M-8 | Samples |
| LM2917MX-8/NOPB | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM29 17M-8 | Samples |
| LM2917MX/NOPB | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | LM2917M | Samples |



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PACKAGE OPTION ADDENDUM

7-Oct-2013

| Orderable Device | Status | Package Type | | Pins | Package | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|--------|--------------|---------|------|---------|----------------------------|------------------|------------------|--------------|----------------|---------|
| | (1) | | Drawing | | Qty | (2) | | (3) | | (4/5) | |
| LM2917N | ACTIVE | PDIP | NFF | 14 | 25 | TBD | Call TI | Call TI | -40 to 85 | LM2917N | Samples |
| LM2917N-8 | ACTIVE | PDIP | Р | 8 | 40 | TBD | Call TI | Call TI | -40 to 85 | LM 2917N-8 | Samples |
| LM2917N-8/NOPB | ACTIVE | PDIP | Р | 8 | 40 | Green (RoHS & no Sb/Br) | CU SN | Level-1-NA-UNLIM | -40 to 85 | LM 2917N-8 | Samples |
| LM2917N/NOPB | ACTIVE | PDIP | NFF | 14 | 25 | Green (RoHS & no Sb/Br) | CU SN | Level-1-NA-UNLIM | -40 to 85 | LM2917N | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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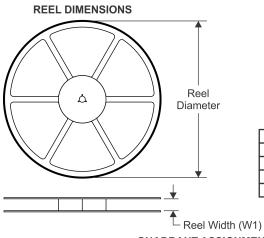


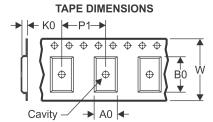
7-Oct-2013

PACKAGE MATERIALS INFORMATION

www.ti.com 23-Sep-2013

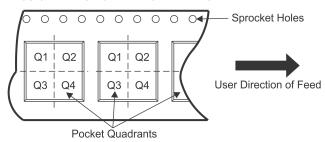
TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|---|
| | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

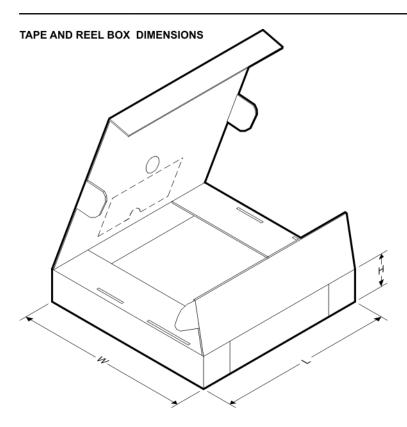
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| LM2907MX | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.35 | 2.3 | 8.0 | 16.0 | Q1 |
| LM2907MX-8/NOPB | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |
| LM2907MX/NOPB | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.35 | 2.3 | 8.0 | 16.0 | Q1 |
| LM2917MX-8 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |
| LM2917MX-8/NOPB | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |
| LM2917MX/NOPB | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.35 | 2.3 | 8.0 | 16.0 | Q1 |

www.ti.com 23-Sep-2013



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM2907MX | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 35.0 |
| LM2907MX-8/NOPB | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| LM2907MX/NOPB | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 35.0 |
| LM2917MX-8 | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| LM2917MX-8/NOPB | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| LM2917MX/NOPB | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 35.0 |

P (R-PDIP-T8)

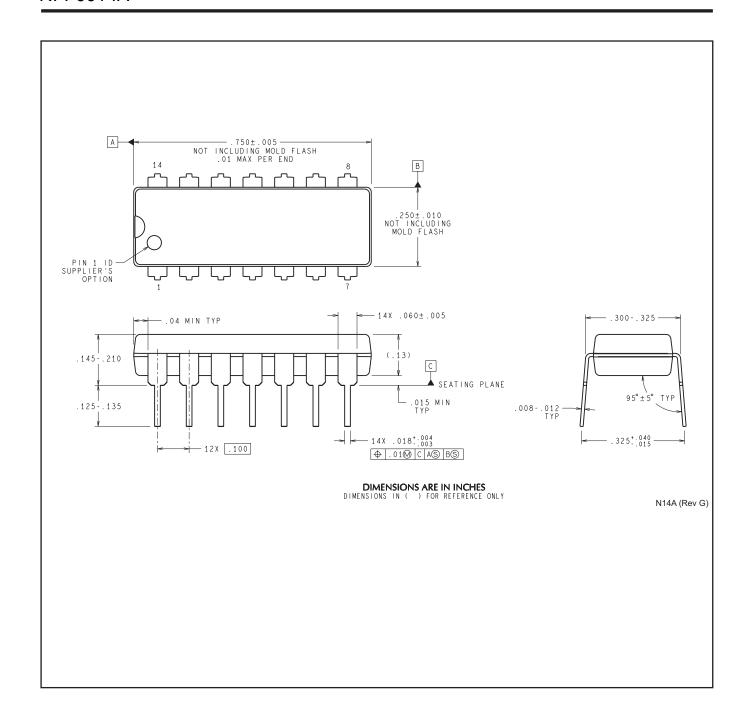
PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.

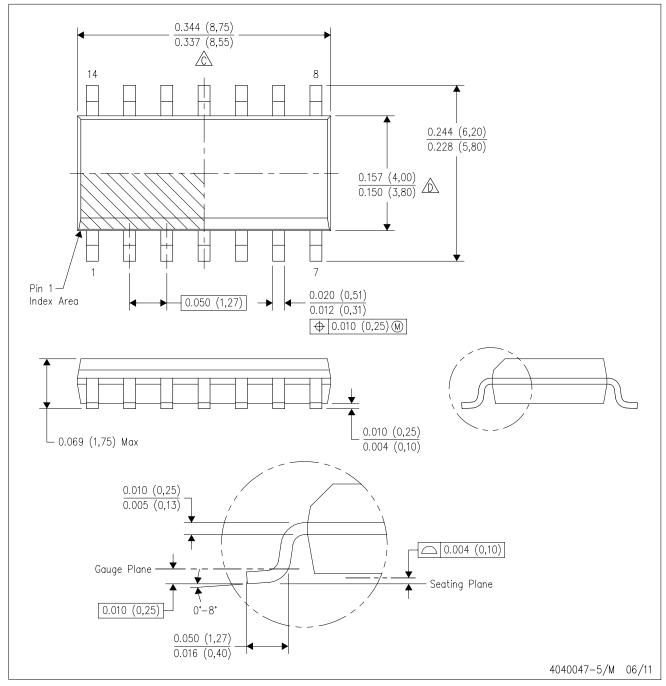






D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



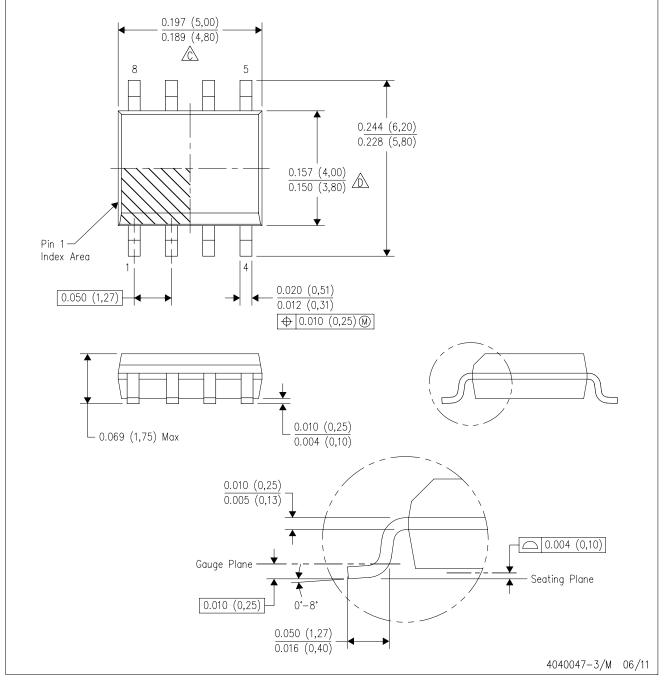
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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